SQF-C8M 760

PCle Gen.3 x4 M.2 2280 SSD



Features

- NGFF M.2 2280 (M Key)
- Compliant with NVMe 1.4
- AES-256 Support & TCG-OPAL Compliant
- 20 to +75 °C (Withstand peak at up to -40°C or 85°C for 1hr)
- Supports LDCP & RAID ECC
- SQ-Power with Dynamic clock adjustment
- GUI management tool & software API package

RoHS CEFCC







Specifications

Connect Type	NGFF M Key
Flash type	3D TLC BiCS5
Capacity	128GB ~ 2TB
Transfer Mode	PCIe Gen.3 x4
Max. Power Consumption	Read: 3.8 W, Write: 3.9 W
Sustained R/W Performance (*)	up to 3,400/ 2,800 MB/sec
Operating Temperature	-20 to +75 °C (Withstand peak at up to -40°C or 85°C for 1hr)
Shock Resistance	1,500 G, peak / 0.5 ms; 3 axes
Vibration Resistance	20 G, peak / 7 ~ 2000 Hz; 3 axes
Dimensions (mm)	80.0 x 22.0 x 3.8
GUI management tool	SQ Manager 2.0, Device On
Diagnose	SMART, SQ-Log & SQ-Analyzer

^(*) These values are for reference only; they may change according to the flash memory used.

Ordering Information

PN	Description
SQF-C8MV1F128GDEGQ	SQF PCIe/NVMe M.2 2280 OPAL 760 128G 3D TLC BiCS5 (-20~75°C)
SQF-C8MV2F256GDEGQ	SQF PCIe/NVMe M.2 2280 OPAL 760 256G 3D TLC BiCS5 (-20~75°C)
SQF-C8MV4F512GDEGQ	SQF PCIe/NVMe M.2 2280 OPAL 760 512G 3D TLC BiCS5 (-20-75°C)
SQF-C8MV4F1TDEGQ	SQF PCIe/NVMe M.2 2280 OPAL 760 1T 3D TLC BiCS5 (-20~75°C)
SQF-C8MV4F2TDEGQ	SQF PCIe/NVMe M.2 2280 OPAL 760 2T 3D TLC BiCS5 (-20~75°C)